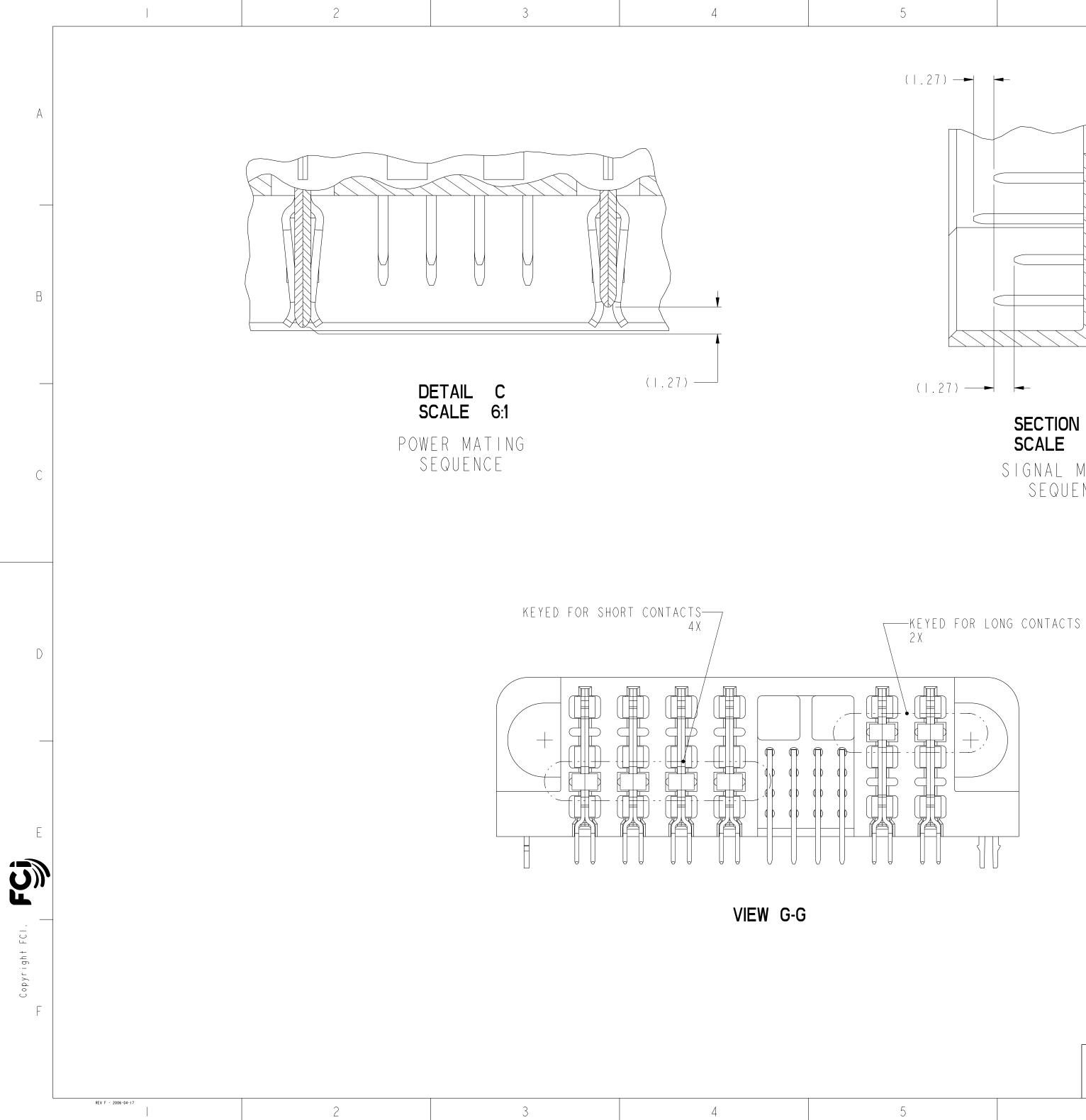
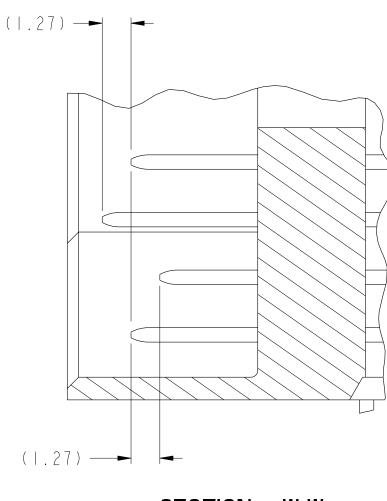


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SECTION W-W SCALE 6:1 SIGNAL MATING SEQUENCE

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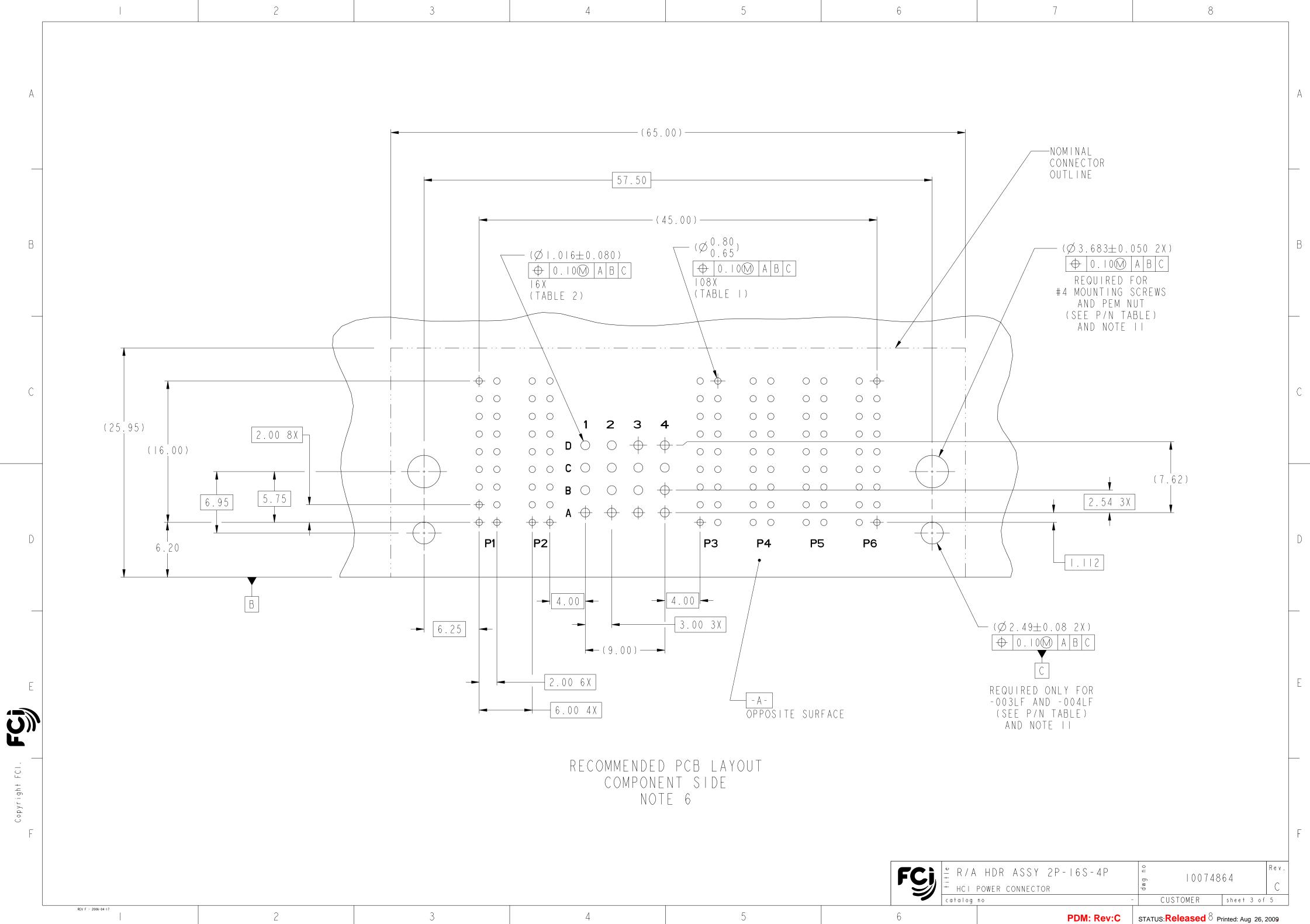
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				DIAT	TABLE I (HCI F ED THROUGH-HOLE				
	TOP LAYER DESCRIPTION	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD	T I N THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMET
	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015					0.65 - 0.8
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050				0.9 - I.5um		0.70 - 0.8
	IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050					0.15 - 0.65um	0.70 - 0.8
	THILE NOT ON OTEVEN								
C	COPPER (SEE NOTE 9)	0.8 -0.86 (0.85 DR)	1 0.075 - 0.050						1 0 10 = 0 0
С	COPPER (SEE NOTE 9) GOLD	0.81-0.86 (0.85 DRILL) 0.81-0.86 (0.85 DRILL)	0.025 - 0.050		0.003 - 0.007	FLASH UP TO 0.0002			
C						FLASH UP TO 0.0002 GNALS)			
С	GOLD				0.003 - 0.007 TABLE 2 (HPC SI	FLASH UP TO 0.0002 GNALS)			0.69 - 0.8 FINISHED
C	GOLD Top layer	0.81-0.86 (0.85 DRILL) DRILLED HOLE	0.025 - 0.050 COPPER	 P L A T T I N - L E A D	O.OO3 - O.OO7 TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL	FLASH UP TO 0.0002 GNALS) REQUIREMENTS GOLD	 T N	 Silver	0.69 - 0.8 FINISHED HOLE DIAMET 0.94 - 1.1
C	GOLD TOP LAYER DESCRIPTION	0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER 1.125-1.175	0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS	O.003 - O.007 TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS	FLASH UP TO 0.0002 GNALS) REQUIREMENTS GOLD THICKNESS	 T N T H I C K N E S S	SILVER THICKNESS	0.69 - 0.8 FINISHED HOLE DIAMET 0.94 - 1.1
C	GOLD TOP LAYER DESCRIPTION TIN-LEAD	0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER 1.125-1.175	0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS 0.005-0.015	O.003 - O.007 TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS 	FLASH UP TO 0.0002 GNALS) REQUIREMENTS GOLD THICKNESS 	 T N T H I C K N E S S	 SILVER THICKNESS 	0.70 - 0.8 0.69 - 0.8 FINISHED HOLE DIAMET 0.94 - 1.1 (Ø.040±.00
	GOLD TOP LAYER DESCRIPTION TIN-LEAD IMMERSION TIN	0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER 1.125-1.175	0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS 0.005-0.015 	O.003 - O.007 TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS 	FLASH UP TO 0.0002 GNALS) REQUIREMENTS GOLD THICKNESS 	 TIN THICKNESS 	 SILVER THICKNESS 	0.69 - 0.8 FINISHED HOLE DIAMET 0.94 - 1.1

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	PART NUMBER	RETENTION CLIPS	#4 SCREW	DIM A (TAIL LEN	T A I L T Y P E		i
	10074864-001LF	NO	YES	3.43	SOLDER TAIL		
	10074864-002LF	NO	YES	4.70	SOLDER TAIL		
Δ	10074864-003LF	YES	NO	3.43	SOLDER TAIL		
	10074864-004LF	YES	NO	4.70	SOLDER TAIL		

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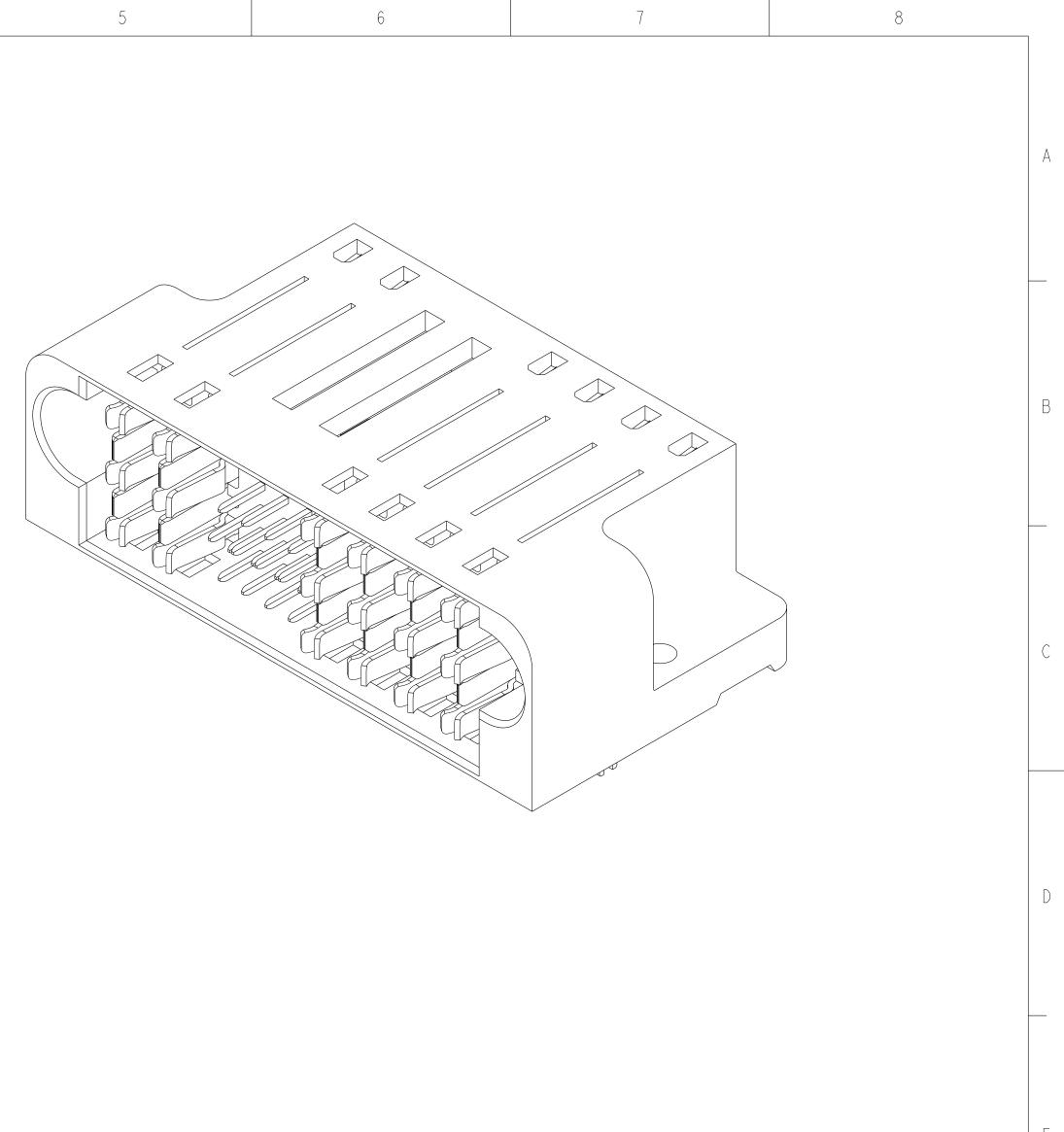
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NOTES:

- I. CONNECTOR MATERIALS: HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK UL 94V-0 COMPLIANT CONTACTS: HIGH PERFORMANCE COPPER ALLOY
- 2. CONTACT FINISH (REF. GS-12-380 SECTION 5.2)
- 3. PRODUCT SPECIFICATION: GS-12-380.
- 4. APPLICATION SPECIFICATION: GS-20-070.
- (5.) PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
- (6.) MINIMUM NOMINAL PCB THICKNESS: 1.6mm
- 7. PACKAGING MEETS FCI SPECIFICATION GS-14-1073.
- (8.) HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
- (9.) COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
- IO. ALL HOLE SIZES ARE FINISHED HOLE SIZES.
- (II.) MOUNTING HOLES ARE UNPLATED.

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